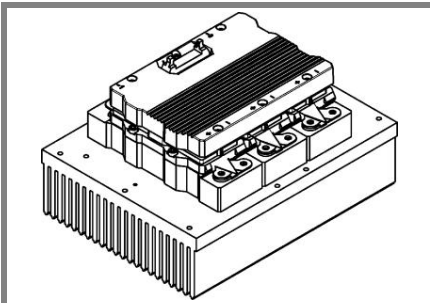


SKiiP 1513GB122-3DL



SKiiP® 3

2-pack-integrated intelligent Power System

Power Section

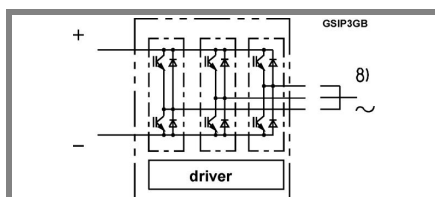
SKiiP 1513GB122-3DL

Data

Power section features

- SKiiP technology inside
- SPT (Soft Punch Trough) IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 3 System)
- IEC 60068-1 (climate) 40/125/56
- UL recognized File no. E63532

- 1) with assembly of suitable MKP capacitor per terminal
- 8) AC connection busbars must be connected by the user; copper busbars available on request



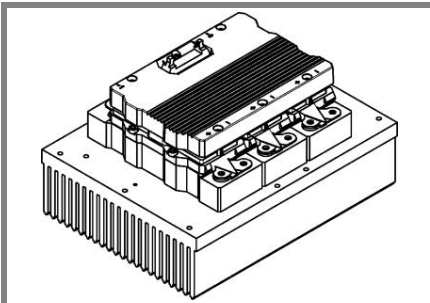
Case S33

| Absolute Maximum Ratings | | $T_s = 25^\circ\text{C}$ unless otherwise specified | |
|--------------------------|---|---|-------------------|
| Symbol | Conditions | Values | Units |
| IGBT | | | |
| V_{CES} | Operating DC link voltage | 1200 | V |
| $V_{CC}^{1)}$ | | 900 | V |
| V_{GES} | | ± 20 | V |
| I_C | $T_s = 25 (70)^\circ\text{C}$ | 1500 (1125) | A |
| Inverse diode | | | |
| $I_F = -I_C$ | $T_s = 25 (70)^\circ\text{C}$ | 1340 (1020) | A |
| I_{FSM} | $T_j = 150^\circ\text{C}$, $t_p = 10\text{ ms}$; sin | 10200 | A |
| I^2t (Diode) | Diode, $T_j = 150^\circ\text{C}$, 10 ms | 520 | kA ² s |
| T_j , (T_{stg}) | rms, AC, 1 min, main terminals to heat sink per AC terminal, rms, $T_s = 70^\circ\text{C}$, $T_{terminal} < 115^\circ\text{C}$ | - 40 ... + 150 (125) | $^\circ\text{C}$ |
| V_{isol} | | 3000 | V |
| $I_{AC-terminal}$ | | 400 | A |

| Characteristics | | $T_s = 25^\circ\text{C}$ unless otherwise specified | | | | | | | |
|---|---|---|------------|-----------|------------|-----|------|------|------|
| Symbol | Conditions | min. | typ. | max. | Units | | | | |
| IGBT | | | | | | | | | |
| V_{CEsat} | $I_C = 900\text{ A}$, $T_j = 25 (125)^\circ\text{C}$; measured at terminal | | 2,3 (2,5) | 2,6 | V | | | | |
| V_{CEO} | $T_j = 25 (125)^\circ\text{C}$; at terminal | | 1,1 (1) | 1,3 (1,2) | V | | | | |
| r_{CE} | $T_j = 25 (125)^\circ\text{C}$; at terminal | | 1,3 (1,7) | 1,5 (1,9) | m Ω | | | | |
| I_{CES} | $V_{GE} = 0\text{ V}$, $V_{CE} = V_{CES}$, $T_j = 25 (125)^\circ\text{C}$ | | 3,6 (108) | | mA | | | | |
| $E_{on} + E_{off}$ | $I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$ | | 270 | | mJ | | | | |
| | $T_j = 125^\circ\text{C}$, $V_{CC} = 900\text{ V}$ | | 476 | | mJ | | | | |
| R_{CC+EE} | terminal chip, $T_j = 25^\circ\text{C}$ | | 0,17 | | m Ω | | | | |
| L_{CE} | top, bottom | | 4 | | nH | | | | |
| C_{CHC} | per phase, AC-side | | 5,1 | | nF | | | | |
| Inverse diode | | | | | | | | | |
| $V_F = V_{EC}$ | $I_F = 900\text{ A}$, $T_j = 25 (125)^\circ\text{C}$ measured at terminal | | 1,95 (1,7) | 2,1 | V | | | | |
| V_{TO} | $T_j = 25 (125)^\circ\text{C}$ | | 1,1 (0,8) | 1,2 (0,9) | V | | | | |
| r_T | $T_j = 25 (125)^\circ\text{C}$ | | 0,9 (1) | 1 (1,2) | m Ω | | | | |
| E_{rr} | $I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$ | | 72 | | mJ | | | | |
| | $T_j = 125^\circ\text{C}$, $V_{CC} = 900\text{ V}$ | | 92 | | mJ | | | | |
| Mechanical data | | | | | | | | | |
| M_{dc} | DC terminals, SI Units | 6 | | 8 | Nm | | | | |
| M_{ac} | AC terminals, SI Units | 13 | | 15 | Nm | | | | |
| w | SKiiP® 3 System w/o heat sink | | 2,4 | | kg | | | | |
| w | heat sink | | 7,5 | | kg | | | | |
| Thermal characteristics (PX 16 heat sink with fan SKF 16B-230-1); "s" reference to heat sink; "r" reference to built-in temperature sensor (acc. IEC 60747-15) | | | | | | | | | |
| $R_{th(j-s)I}$ | per IGBT | | | 0,02 | K/W | | | | |
| $R_{th(j-s)D}$ | per diode | | | 0,038 | K/W | | | | |
| Z_{th} | R_i (mK/W) (max. values) | tau _i (s) | | | | | | | |
| | | 1 | 2 | 3 | 4 | | | | |
| $Z_{th(j-r)I}$ | | 3,4 | 9,6 | 7 | 0 | 363 | 0,18 | 0,04 | 1 |
| $Z_{th(j-r)D}$ | | 12 | 12 | 18 | 20 | 30 | 5 | 0,25 | 0,04 |
| $Z_{th(r-a)}$ | | 2,1 | 20 | 5,5 | 1,4 | 210 | 85 | 11 | 0,4 |

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SKiiP 1513GB122-3DL



SKiiP® 3

2-pack-integrated intelligent Power System

2-pack
integrated gate driver
SKiiP 1513GB122-3DL

Data

Gate driver features

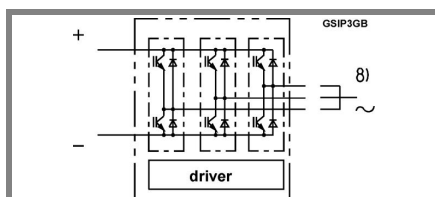
- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protection against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 60068-1 (climate) 40/85/56
- UL recognized file no. 242581

| Absolute Maximum Ratings | | $T_a = 25\text{ °C}$ unless otherwise specified | |
|--------------------------|---|---|-------------|
| Symbol | Conditions | Values | Units |
| V_{S2} | unstabilized 24 V power supply | 30 | V |
| V_i | input signal voltage (high) | 15 + 0,3 | V |
| dv/dt | secondary to primary side | 75 | kV/ μ s |
| V_{isolIO} | input / output (AC, rms, 2) | 3000 | V |
| V_{isolPD} | partial discharge extinction voltage, rms, $Q_{PD} \leq 10\text{ pC}$; | 1170 | V |
| V_{isol12} | output 1 / output 2 (AC, rms, 2 s) | 1500 | V |
| f_{sw} | switching frequency | 10 | kHz |
| f_{out} | output frequency for $I_{peak(1)}=I_C$ | 10 | kHz |
| T_{op} (T_{stg}) | operating / storage temperature | - 40 ... + 85 | °C |

| Characteristics | | $(T_a = 25\text{ °C})$ | | | |
|-----------------|---|-------------------------------------|-----------------|------|------------|
| Symbol | Conditions | min. | typ. | max. | Units |
| V_{S2} | supply voltage non stabilized | 13 | 24 | 30 | V |
| I_{S2} | $V_{S2} = 24\text{ V}$ | $278+29*f/kHz+0,00015*(I_{AC}/A)^2$ | | | mA |
| V_{iT+} | input threshold voltage (High) | | | 12,3 | V |
| V_{iT-} | input threshold voltage (Low) | 4,6 | | | V |
| R_{IN} | input resistance | | 10 | | k Ω |
| C_{IN} | input capacitance | | 1 | | nF |
| $t_{d(on)IO}$ | input-output turn-on propagation time | | 1,3 | | μ s |
| $t_{d(off)IO}$ | input-output turn-off propagation time | | 1,3 | | μ s |
| $t_{pERRRESET}$ | error memory reset time | | 9 | | μ s |
| t_{TD} | top / bottom switch interlock time | | 3,3 | | μ s |
| $I_{analogOUT}$ | max. 5mA; 8 V corresponds to 15 V supply voltage for external components | | 1500 | | A |
| I_{s1out} | max. load current | | | 50 | mA |
| I_{TRIPSC} | over current trip level ($I_{analog OUT} = 10\text{ V}$) | | 1875 | | A |
| T_{tp} | over temperature protection | 110 | | 120 | °C |
| U_{DCTRIP} | U_{DC} -protection ($U_{analog OUT} = 9\text{ V}$); (option for GB types) | | not implemented | | V |

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Case S33